



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Mc CORMACK, MARK JEE PROCESS.
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Filed: 4/12/01

For: METHOD AND STRUCTURE OF
DEPOSITING SOLDER BUMPS
ON A WAFER (99-32)

Group Art Unit: 2812

Attorney Docket No: P53945US0

US PATENT &
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Commissioner for Patents
Washington, D.C. 20231

Sir:

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